

The listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A thin film integrated circuit device comprising:  
a metal oxide;  
an insulating film over the metal oxide;  
~~a plurality of semiconductor films isolated from one another,~~ film, a gate insulating film, and a gate electrode which are provided over ~~one surface of the~~ insulating film; and  
a thin film integrated circuit having the ~~plurality of semiconductor films; and a metal oxide provided over the other surface of the insulating film~~ film, the gate insulating film, and the gate electrode.
2. (Original) A thin film integrated circuit device according to claim 1, wherein the metal oxide comprises WO<sub>2</sub> or WO<sub>3</sub>.
3. (Original) A thin film integrated circuit device according to claim 1, wherein the metal oxide is an oxide of an element selected from the group consisting of W, Ti, Ta, Mo, Nd, Ni, Co, Zr, Zn, Ru, Rh, Pd, Os, and Ir; an alloy containing the metal as a main component; or a chemical compound thereof.
4. (Currently Amended) A thin film integrated circuit device according to claim 1, wherein ~~each of the plurality of semiconductor~~ [[films]] film functions as an active region.

5. (Currently Amended) A thin film integrated circuit device according to claim 1, wherein ~~each of the plurality of semiconductor [[films]]~~ film functions as a channel region.

6. (Currently Amended) An IC label comprising:

a metal oxide;

an insulating film over the metal oxide;

~~a plurality of semiconductor films isolated from one another,~~ film, a gate insulating film, and a gate electrode which are provided over ~~one surface of the~~ insulating film; and

~~a thin film integrated circuit having the plurality of semiconductor films as an active region; and an affixing means for affixing a surface of the IC label to a container~~ film, the gate insulating film, and the gate electrode.

7. (Original) An IC label according to claim 6, wherein the IC label is a contactless type.

8. (Currently Amended) An IC label according to claim 6, wherein ~~the other~~ a surface of the IC label can be printed with a character, a letter, text, a symbol, or a diagram.

9. (Currently Amended) An IC label comprising a contactless thin film integrated circuit, ~~said IC label being adhered to a container,~~

wherein the thin film integrated circuit comprises:

a metal oxide;

an insulating film over the metal oxide;

~~a plurality of semiconductor film isolated from one another which are provided~~ over ~~[[an]]~~ the insulating film ~~as an active region;~~

a gate electrode provided over the semiconductor film with a gate insulating film interposed between the semiconductor layer and the gate electrode; and  
an antenna in a same layer as the gate electrode.

10. (Original) An IC label according to claim 9, wherein the antenna is formed from a same material as the gate electrode.

11. (Original) An IC label according to claim 9, wherein the antenna comprises a conductive paste.

12. (Currently Amended) An IC label comprising a contactless thin film integrated circuit, ~~said IC label being adhered to a container,~~  
wherein the thin film integrated circuit comprises:  
a metal oxide;  
an insulating film over the metal oxide;  
~~a plurality of semiconductor film, isolated from one another~~ a gate insulating film,  
and a gate electrode which are provided over ~~[[an]]~~ the insulating film ~~as an active region;~~  
a wiring connected to an impurity region of the semiconductor film; and  
an antenna in a same layer as the wiring.

13. (Currently Amended) An IC label according to claim 12, wherein the antenna comprises a same material as the ~~[[gate]]~~ wiring.

14. (Original) An IC label according to claim 12, wherein the antenna comprises a conductive paste.

15. (Currently Amended) A container comprising:

a metal oxide;

an insulating film over the metal oxide;

a plurality of semiconductor films isolated from one another film, a gate insulating film, and a gate electrode, which are provided over ~~one surface of~~ the insulating film;  
and

a thin film integrated circuit having the ~~plurality of semiconductor films as an active region~~ film, the gate insulating film, and the gate electrode,

wherein the thin film integrated circuit is adhered to the container.

16. (Original) A container according to claim 15, wherein the thin film integrated circuit is covered by a label.

17. (Original) A container according to claim 16, wherein a protective film having a DLC film or a CN film is provided between the thin film integrated circuit and the label.

18. (Original) A container according to claim 15, wherein the thin film integrated circuit is held between a first label and a second label, and the second label is affixed to the thin film integrated circuit with an adhesive agent.

19. (Currently Amended) A container according to claim 15,  
~~wherein a metal oxide is provided over the other side of the insulating film; and~~  
wherein the metal oxide is adhered to the container.

20. (Currently Amended) A container comprising a contactless thin film integrated circuit ~~that is adhered to a container,~~

wherein the thin film integrated circuit comprises:

a metal oxide;

an insulating film over the metal oxide;

~~a plurality of semiconductor films isolated from one another which are~~ film  
provided over one surface of an the insulating film as an active region;

a gate electrode that is provided over the ~~plurality of semiconductor~~ [[films]] film;  
and

an antenna that is provided in a same layer as the gate electrode,  
~~wherein the other surface of the insulating film comprises a metal oxide.~~

21. (Original) A container according to claim 20, wherein the thin film integrated circuit is covered by a label.

22. (Original) A container according to claim 21, wherein a protective film having a DLC film or a CN film is provided between the thin film integrated circuit and the label.

23. (Original) A container according to claim 20, wherein the thin film integrated circuit is held between a first label and a second label, and the second label is affixed to the thin film integrated circuit with an adhesive agent.

24. (Currently Amended) A container comprising a contactless thin film integrated circuit ~~that is adhered to a container,~~

wherein the thin film integrated circuit comprises:

a metal oxide;

an insulating film over the metal oxide;

wherein the thin film integrated circuit comprises:

~~a plurality of semiconductor films isolated from one another~~ film, a gate insulating film, and a gate electrode which are provided over one surface of an insulating film as an active region;

a wiring provided over the ~~plurality of semiconductor~~ [[films]] film; and

an antenna provided in a same layer as the wiring;

~~wherein the other surface of the insulating film comprises a metal oxide.~~

25. (Original) A container according to claim 24, wherein the thin film integrated circuit is covered by a label.

26. (Original) A container according to claim 25, wherein a protective film having a DLC film or a CN film is provided between the thin film integrated circuit and the label.

27. (Original) A container according to claim 24, wherein the thin film integrated circuit is held between a first label and a second label, and the second label is affixed to the thin film integrated circuit with an adhesive agent.

28.-60. (Canceled)